

**REMARKS**

**Introduction**

This paper has been filed concurrently with a Petition to Revive for Unintentional Abandonment and the proper fee as well as a Formal Drawings Transmittal and an Information Disclosure Statement.

This paper is responsive to the Office Action mailed December 4, 2002. Through no fault of applicant the case was allowed to lapse and there was apparently an attempt made by prior counsel to revive it in December, 2003.

The Applicant thanks the Examiner for the careful review and consideration of this application. Applicant has conducted its own careful review of the application specification and claims. A number of corrections have been made to the specification and claims in order to improve readability and to correct typographical errors. No new matter has been introduced by these amendments. If the Examiner would like a substitute specification due to the relatively large number of amendments, applicant stands willing to provide one upon request.

Claims 1 – 10 are pending. No claims are cancelled by this amendment. Claims 1 -5 and 8 - 10 are hereby amended. The text of claims 6 – 7 is unchanged, but their meaning is changed because they depend from amended claims.

**Drawings**

Corrected formal drawings were requested in the office action. The word “outtake” was changed to “outlet” in FIG. 1 to make it consistent with the amended specification. Such formal drawings are filed herewith. No new matter has been introduced.

**Claim Rejections – 35 U.S.C. Sec. 112**

Claims 8 – 10 stand rejected under 35 U.S.C. Sec. 112, first paragraph, allegedly:  
“because the specification, while being enabling for the use of a heated gas, does not reasonably provide enablement for any other non-specified method of changing the deposited material into a gaseous material. The specification does not enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to practice the invention commensurate in scope with these claims. The specification provides only for the use of the heated gas and fails to provide any guidance regarding any other method for changing the deposited material into a gaseous material. Thereby, an ordinary artisan would not be able to practice the claimed invention without undue experimentation.”

Claims 8 – 10 have been amended to specifically recite that the “changing” occurs by heating the deposited material with a gaseous flow. Accordingly, the claims now meet the statutory requirements and this rejection, being moot, should now be withdrawn.

**The 35 U.S.C. Sec. 102(b) Rejection**

Claims 1-10 stand rejected under 35 U.S.C. §102(b) as allegedly being anticipated by Chen et al (US Patent No. 5,759,287).

According to the Office Action: “Chen et al. teach an apparatus and a method as claimed. See entire reference, especially columns 2-4.”

According to the M.P.E.P., a claim is anticipated under 35 U.S.C. Sec. 102(a), (b) and (e) only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference. M.P.E.P. Sec. 2131. *Verdegaal Bros. v. Union Oil Co. of California*, 814 F.2d 628, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987).

Chen et al. (USP 5,536,330) is directed to purging and pumping a vacuum chamber to ultra-high vacuum. Chen et al. uses a heated non-reactive gas such as Argon “to entrain and remove desorbed contaminants”. The process is used to pump the chamber down from atmosphere after it has been opened and remove gasses and water that contaminated the chamber upon being opened, see, generally, Cols. 2 – 5. It is particularly directed to getting water molecules and the like out of the chamber, rather than the deposited material referred to in the presently presented claims.

Claim 1 recited a system for removing deposited material buildup by use of heated gas to sublimate or evaporate the deposited material and remove it by means of the heated gas flow.

Chen et al. does not do this because Chen et al. does not disclose any operation by which it sublimated or evaporates deposited material on the interior walls of the device and removes the material by heated gas flow. The claimed device operates to remove deposited material without opening the chamber to atmospheric pressure.

Claim 2 recites a process in which material on the surface of a chamber is removed. In that method, "deposited material" on the "surface of the interior wall" is sublimat[ed] or evaporat[ed], based on the combination of the heating and the atmospheric pressure" produced in the chamber.

In contradistinction Chen makes no mention of material deposited on a surface of an interior wall, sublimating the deposited material from the surface of the interior wall, or evaporating the deposited material from the interior wall. Specifically, Chen is directed to the preparation of a chamber after a wet-clean. Accordingly the rejections of Claims 1-10 as recited in this Action do not establish a proper case of anticipation. In even more specificity, Chen refers to removing adsorbed materials.

Accordingly Claim 2 is believed to be allowable over the cited art. Applicant respectfully traverses the rejection of Claim 2.

Claims 8 and 9

Claims 8 and 9 have many of the similar properties of Claim 1 above, such as "changing the material deposited on the interior walls of the device into a gaseous material[.]" For many of the same reasons noted above in relation Claim 1, Claims 8 and 9 are believed to be allowable.

Accordingly Claims 8 and 9 are believed to be allowable over the cited art. Applicant respectfully traverses the rejection of Claims 8 and 9.

Claim 10

Claim 10 is directed to a method of running a semiconductor fabrication device. The steps include: producing a batch of semiconductor devices; *changing the material deposited on the interior walls of the device into a gaseous material by heating the material with a gaseous flow prior to unsealing the production device to the external environment*; and concurrently with changing, removing the gaseous material from the device with the gaseous flow. Nothing in Chen seems to state or suggest the step of changing the material deposited on the interior walls *prior to unsealing the production device*.

Accordingly Claim 10 is believed to be allowable over the cited art. Applicant respectfully traverses the rejection of Claim 10.

Dependent Claims 3 – 7

Dependent claims 3 – 7 are dependent upon claim 2 which has been shown to be allowable above. For the same reasons, then, claims 3 – 7 are allowable as well.

Appl. No. 09/943,569  
Amdt. Dated April 15, 2004  
Reply to Office action of December 4, 2002

YIELD-0002 (036134-000003)

### III. Conclusion

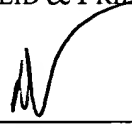
It is believed that this Response places the above-identified patent application into condition for allowance. Early favorable consideration of this Amendment is earnestly solicited.

If, in the opinion of the Examiner, an interview would expedite the prosecution of this application, the Examiner is invited to call the undersigned attorney at the number indicated below.

This response is submitted with the proper fees, and the petition to revive. The Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Deposit Account No. 50-1698.

Respectfully submitted,  
THELEN REID & PRIEST-LLP

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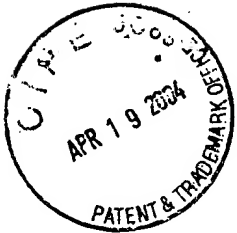


Fig. 1

